

PCN97009A Data

Thermal Data for Thermally Enhanced Plastic Quad Flat Pack (PQFP)

Still Air Data Comparison:

	HQFP (Current Non-Insulated)	HQFP (Insulated)	PQFP (Std)
	JA (°C/watt)	JA (°C/watt)	JA (°C/watt)
208 pins	14 - 15	14 - 16	25 - 32
240 pins	11 - 14	11 - 15	18 - 28

Notes:

JC Data:

1. HQFP (Thermally Enhanced) = 0.7 - 1.2°C/watt, typical.
PQFP (Standard PQFP) = 2.0 - 7.0°C/watt, typical.
2. Test Conditions per JEDEC JC15.1.
3. Data measured using a 4-layer test board.
4. Used Delco Thermal Die. Die sizes vary, compatible to Xilinx device sizes.